

Approved by:

Checked by:

Issued by:

SPECIFICATION

MODEL: HD F927A(F11)

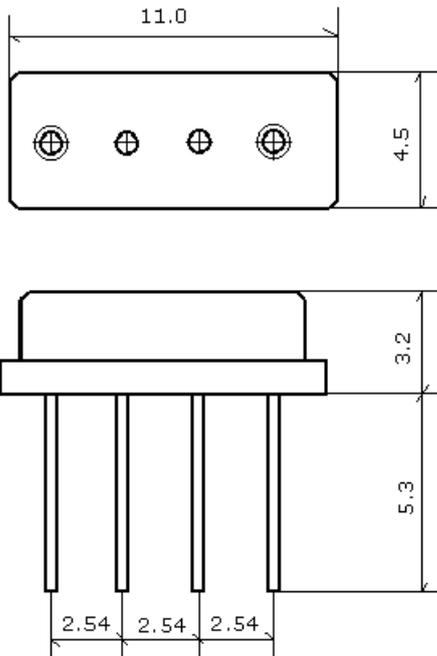


SHOULDER ELECTRONIC LIMITED

1. Package Dimension

Unit:mm

(F-11)



NO	Function
1	Input
2	Ground
3	Ground
4	Output

2. Marking

HD F927A

- 1.Color: Black or Blue
- 2.927: Center Frequency(MHz)

3. Performance

3.1 Application

Low-Loss SAW Filter of cordless system.
Center Frequency:927 MHz

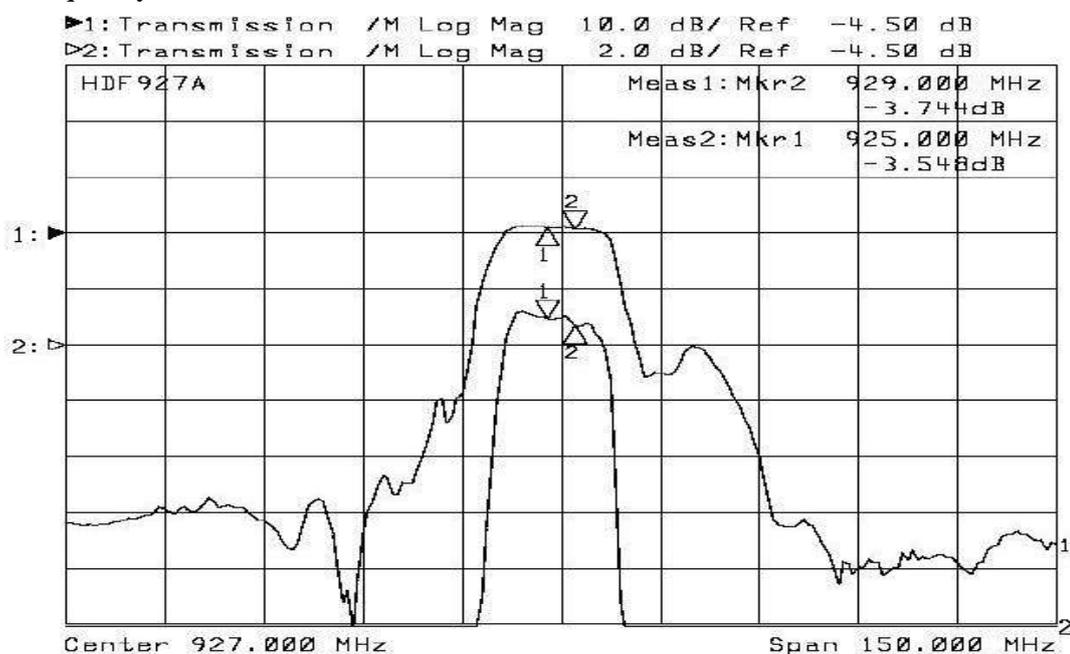
3.2 Maximum Rating

Operation Temperature Range	-10°C to +70°C
Storage Temperature Range	-40°Cto +85°C
DC. Voltage	10 V. max.
Maximum Input Power	10dBm

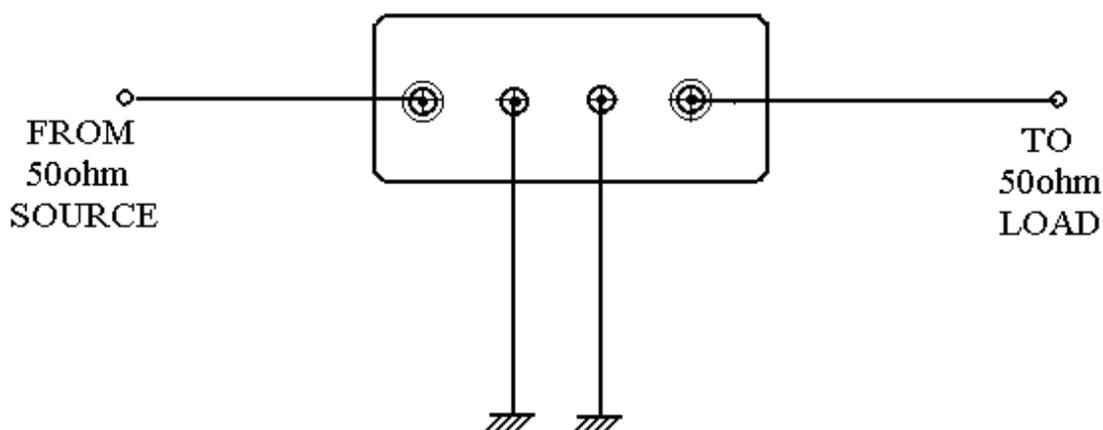
3.3 Electronic Characteristics

Item	Specification
Center Frequency(f_0)	927 MHz
Insertion Loss (925.70~929.50 MHz)	4.0dBmax
Pass Band Ripple (925.70~929.50 MHz)	1.5dBmax
Ripple Deviation 882~886 MHz	45dBmin
904~907 MHz	35dBmin
947~950 MHz	35dBmin
950~952 MHz	35dBmin
968~972 MHz	40dBmin
Terminating Impedance	50 Ω
Operating Temperature Range	-10°C to +70°C

3.4 Frequency Characteristics



3.5 Test Circuit



4. ENVIRONMENTAL CHARACTERISTICS

4-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in table 1.

4-2 Low temperature exposure

Subject the device to -20°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in table 1.

4-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +80°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in table 1.

4-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C \pm 10°C for 10 \pm 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in table 1.

4-5 Solderability

Subject the device terminals into the solder bath at 245°C \pm 5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in table 1.

4-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in table 1.

4-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in table 1.

4-8 Lead fatigue

4-8-1 Pulling test

Weight along with the direction of lead without an shock 1kg. The device shall satisfy all the initial Characteristics.

4-8-2 Bending test

Lead shall be subject to withstand against 90°C bending with 450g weight in the direction of thickness. This operation shall be done toward

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered . Please avoid soldering another part of component.